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(54) WIRING BOARD, CORE BOARD, AND THEIR MANUFACTURE

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a wiring board having a structure which has a condenser built near a mounted IC chip, which is easily manufactured with high production yield, and a reduced loss in cost, even if a nonconformity of capacitor is found in a manufacturing process, a core board using the wiring board, and a method of manufacturing the core board easily at a low cost.

SOLUTION: A wiring board 600 has a core board 610, resin-insulating layers 621, 631, 641, 651 laminated on each of the obverse and reverse surfaces 610A, 610B of the core board 110, and wiring layers 625, 635. The core board 610 has a base metal plate 601, a plurality of composite dielectric layers 611, 612, 613, 614 laminated alternately on the base metal plate 601 and its obverse and reverse surfaces 601A, 601B and containing epoxy resin and high dielectric power, and a plurality of metal layers 602, 603, 604, 605 each of which is thinner than the base metal plate 601, wherein these layers are face opposite each other with the composite dielectric layers 611 white sandwiching the layers 611 to constitute a laminated condenser C61.

